

Electronic Patent Application Fee Transmittal

Application Number:	09590897			
Filing Date:	09-Jun-2000			
Title of Invention:	SEALING STRUCTURE FOR MULTI-CHIP MODULE			
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Filer:	Robert C. Colwell/Margaret Stephan			
Attorney Docket Number:	16869P-010700US			
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Utility under 35 USC 111(a) Filing Fees				
Description	Fee Code	Quantity	Amount	Sub-Total in USD(\$)
Basic Filing:				
Pages:				
Claims:				
Miscellaneous-Filing:				
Petition:				
Patent-Appeals-and-Interference:				
Post-Allowance-and-Post-Issuance:				
Utility Appl issue fee	1501	1	1510	1510
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Printed copy of patent - no color	8001	5	3	15
Total in USD (\$)				1825